

CBR02C379B3GAC

General Information

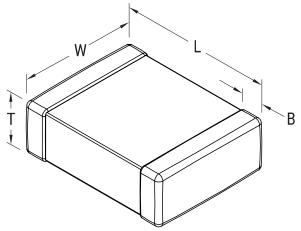
Series

Style

CBR-SMD RF COG, Ceramic, 3.7 pF, +/-0.1 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0201

CBR-SMD RF COG

SMD Chip



Click here for the 3D model.

Dimensions	
Chip Size	0201
L	0.6mm +/-0.03mm
W	0.3mm +/-0.03mm
Т	0.3mm +/-0.03mm
В	0.15mm +/-0.05mm

15000

Plastic Tape

Packaging Specifications	
T&R, 180mm,	

Packaging Quantity

Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	0.3 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1
Specifications	
Capacitance	3.7 pF
Tolerance	+/-0.1 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG

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Tolerance	+/-0.1 pF
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	COG
Dissipation Factor	0.211%
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	10 GOhms
Quality Factor	474

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